

ABSTRACT OF DISCLOSURE

Method and apparatus for interfacing a circuit, such as a microcircuit, with an IC. The circuit is formed on a thick film dielectric structure supported by a substrate having a cut out to receive the IC. A ground plane is formed on the substrate. The thick film dielectric structure abuts the cut out with an area having at least two projections forming at least one recess, the edge of the recess having a conductive layer in electrical communication with the ground plane. A conductive pad on top of the dielectric structure is in electrical communication with the conductive layer in the recess. A ground connection on the IC is connected to the conductive pad thereby grounding the IC.